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Part Number PPC405CR
Revision 1.02 – January 11, 2005

PPC405CR

Data Sheet

PowerPC 405CR Embedded Processor

Features

- PowerPC® 405 32-bit RISC processor core operating up to 266MHz
  - Memory Management Unit
  - 16KB instruction and 8KB data caches
  - Multiply-Accumulate (MAC) function, including fast multiply unit
  - Programmable Timers
- Synchronous DRAM (SDRAM) interface operating up to 133MHz
  - 32-bit interface for non-ECC applications
  - 40-bit interface serves 32 bits of data plus 8 check bits for ECC applications
- External Peripheral Bus
  - Flash ROM/Boot ROM interface
  - Direct support for 8-, 16-, or 32-bit SRAM and external peripherals
  - Up to eight devices
  - External Mastering supported
- DMA support for external peripherals, internal UART and memory
  - Scatter-gather chaining supported
  - Four channels
- Programmable Interrupt Controller supports interrupts from a variety of sources
  - Supports 7 external and 10 internal interrupts
  - Edge triggered or level-sensitive
  - Positive or negative active
  - Non-critical or critical interrupt to processor core
  - Programmable critical interrupt priority ordering
- Two serial ports (16550 compatible UART)
- One IIC interface
- General Purpose I/O (GPIO) available
- Supports JTAG for board level testing
- Internal Processor Local Bus (PLB) runs at SDRAM interface frequency

Description

The PowerPC 405CR (PPC405CR) is a 32-bit RISC embedded controller. High performance, peripheral integration, and low cost make the device ideal for wired communications, network printers, and other computing applications.

This device is an easy upgrade for systems based on PowerPC 403xx embedded processors, while providing a base for custom chip designs.

The controller is powered by a PPC405 embedded core. This core tightly couples a 266 MHz CPU, MMU, instruction and data caches, and debug logic. Fine-tuning of the core reduces data transfer overhead, minimizes pipeline stalls, and improves performance.

The PPC405CR employs the IBM CoreConnect™ bus architecture. This architecture, as implemented on the PPC405CR, consists of a 64-bit, 133-MHz Processor Local Bus (PLB) and a 32-bit, 66-MHz On-Chip Peripheral Bus (OPB). High-performance peripherals attach to the PLB and less performance-critical peripherals attach to the OPB.

Technology: CMOS SA-12E 0.25 μm (0.18 μm L_{eff})

Package: 27mm, 316-ball enhanced plastic ball grid array (E-PBGA)

Power (estimated): Typical 0.8W, Maximum 2.0W at 200MHz.

Contents

Features 1
Description 1
Ordering, PVR, and JTAG Information 4
- **Part Number Key** 4

Address Map Support 6
SDRAM Memory Controller 7
External Peripheral Bus Controller (EBC) 7
DMA Controller 7
UART 8
IIC Bus Interface 8
General Purpose IO (GPIO) Controller 8
Universal Interrupt Controller (UIC) 9
JTAG 9
Pin Lists 11
Signal Descriptions 21
- **Multiplexed Pins** 21
- **Intialization Strapping** 21
- **Pull-Up and Pull-Down Resistors** 21
- **Unused I/Os** 22
- **External Bus Control Signals** 22

Test Conditions 31
Spread Spectrum Clocking 33
Strapping 39
Document Revision History 41

List of Figures

Figure 1. PPC405CR Embedded Controller Functional Block Diagram 5
Figure 2. 27mm, 316-Ball E-PBGA Package 10
Figure 3. Package Thermal Specifications 28
Figure 4. 5V-Tolerant I/O Input Current 30
Figure 5. Timing Waveform 32
Figure 6. Input Setup and Hold Waveform 35
Figure 7. Output Delay and Float Timing Waveform 35

List of Tables

Table 1. System Memory Address Map 4GB System Memory 6
Table 2. DCR Address Map 4KB Device Configuration Register 6
Table 3. Signals Listed Alphabetically 11
Table 4. Signals Listed by Ball Assignment 18
Table 5. Pin Summary 21
Table 6. Signal Functional Description 23
Table 7. Absolute Maximum Ratings 28
Table 8. Recommended DC Operating Conditions 29
Table 9. Input Capacitance 30
Table 10. Clocking Specifications 32
Table 11. Peripheral Interface Clock Timings 34
Table 12. I/O Specifications—All speeds 36
Table 13. I/O Specifications—133 and 200MHz 37
Table 14. I/O Specifications—266MHz 38
Table 15. Strapping Pin Assignments 39

Ordering, PVR, and JTAG Information

Product Name	Order Part Number[1, 2]	Processor Frequency	Package	Rev Level	PVR Value	JTAG ID
PPC405CR	PPC405CR-3BC133C	133MHz	27mm, 316 ball E-PBGA	C	0x40110145	0x42051049
PPC405CR	PPC405CR-3BC133CZ	133MHz	27mm, 316 ball E-PBGA	C	0x40110145	0x42051049
PPC405CR	PPC405CR-3KC133C	133MHz	27mm, 316 ball E-PBGA	C	0x40110145	0x42051049
PPC405CR	PPC405CR-3KC133CZ	133MHz	27mm, 316 ball E-PBGA	C	0x40110145	0x42051049
PPC405CR	PPC405CR-3BC200C	200MHz	27mm, 316 ball E-PBGA	C	0x40110145	0x42051049
PPC405CR	PPC405CR-3BC200CZ	200MHz	27mm, 316 ball E-PBGA	C	0x40110145	0x42051049
PPC405CR	PPC405CR-3KC200C	200MHz	27mm, 316 ball E-PBGA	C	0x40110145	0x42051049
PPC405CR	PPC405CR-3KC200CZ	200MHz	27mm, 316 ball E-PBGA	C	0x40110145	0x42051049
PPC405CR	PPC405CR-3BC266C	266MHz	27mm, 316 ball E-PBGA	C	0x40110145	0x42051049
PPC405CR	PPC405CR-3BC266CZ	266MHz	27mm, 316 ball E-PBGA	C	0x40110145	0x42051049
PPC405CR	PPC405CR-3KC266C	266MHz	27mm, 316 ball E-PBGA	C	0x40110145	0x42051049
PPC405CR	PPC405CR-3KC266CZ	266MHz	27mm, 316 ball E-PBGA	C	0x40110145	0x42051049

Notes: 1. Z at the end of the Order Part Number indicates a tape and reel shipping package. Otherwise, the chips are shipped in a tray.
2. Package type B contains lead; package type K is lead-free.

This section provides the part numbering nomenclature for the PPC405CR. For availability, contact your local AMCC sales office.

Each part number contains a revision code. This refers to the die mask revision number and is specified in the part numbering scheme for identification purposes only.

The PVR (Processor Version Register) is software accessible and contains additional information about the revision level of the part. Refer to the *PPC405CR Embedded Processor User's Manual* for details on the register content.

Part Number Key

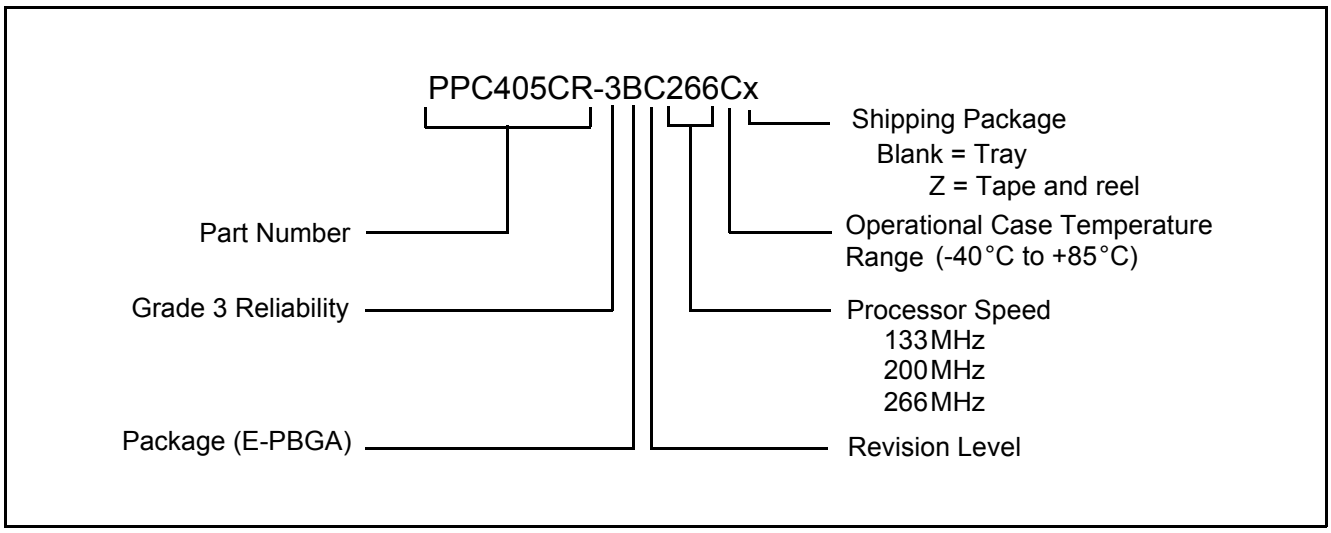
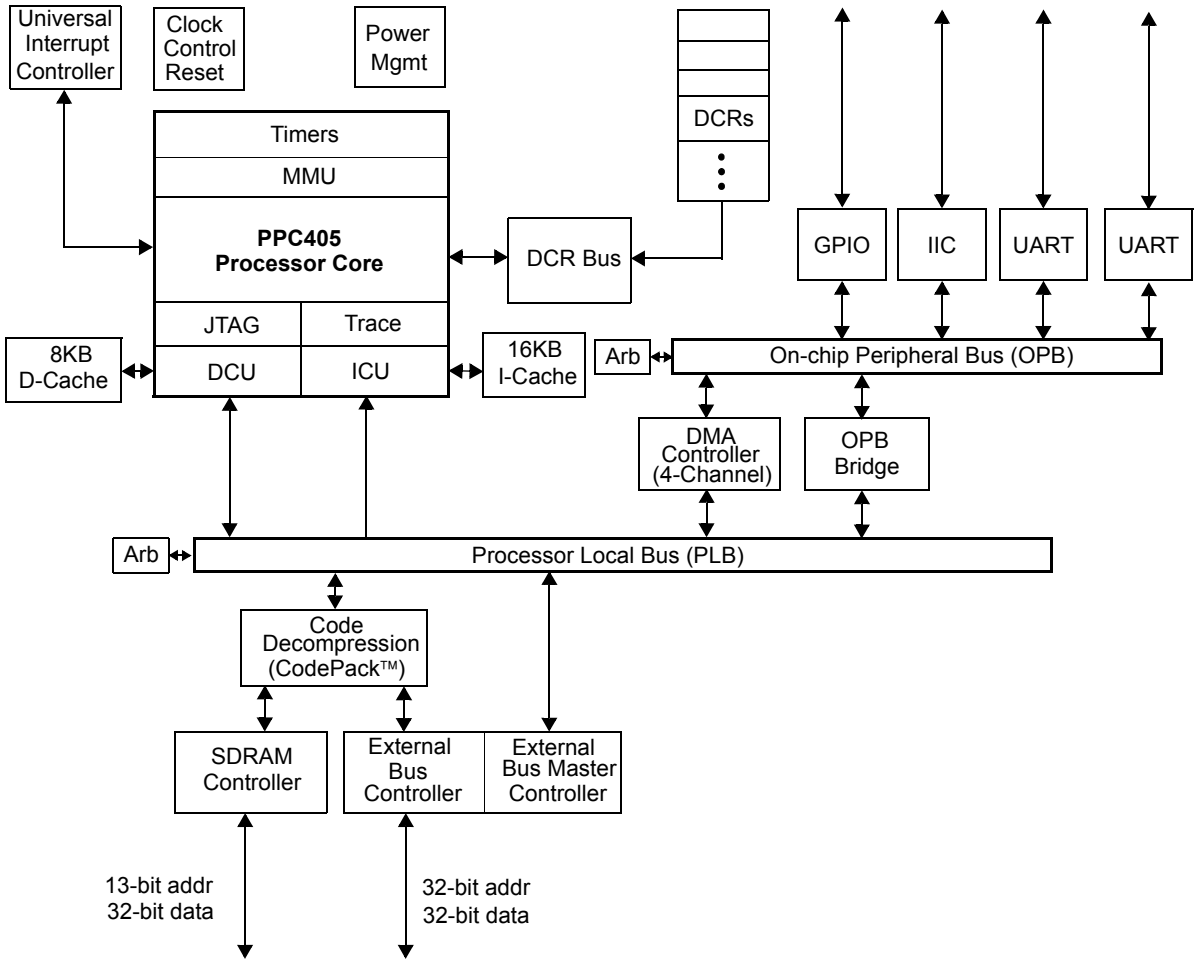


Figure 1. PPC405CR Embedded Controller Functional Block Diagram



The PPC405CR is designed using the IBM Microelectronics Blue Logic® methodology in which major functional blocks are integrated together to create an application-specific ASIC product. This approach provides a consistent way to create complex ASICs using IBM CoreConnect™ Bus Architecture.

Address Map Support

The PPC405CR incorporates two simple and separate address maps. The first address map defines the possible use of address regions that the processor can access. The second address map is for Device Configuration Registers (DCRs). The DCRs are accessed by software running on the PPC405CR processor through the use of **mtdcr** and **mfdcr** instructions.

Table 1. System Memory Address Map (4GB System Memory)

Function	Subfunction	Start Address	End Address	Size
General Use	SDRAM and External Peripherals	0x00000000	0xEF5FFFFF	3830MB
	Note: Any of the address ranges listed at right may be use for any of the above functions.	0xF0000000	0xFFFFFFFF	256MB
Boot-up	Peripheral Bus Boot [1]	0xFFE00000	0xFFFFFFFF	2MB
Internal Peripherals	UART0	0xEF600300	0xEF600307	8B
	UART1	0xEF600400	0xEF600407	8B
	IIC0	0xEF600500	0xEF60051F	32B
	OPB Arbiter	0xEF600600	0xEF60063F	64B
	GPIO Controller Registers	0xEF600700	0xEF60077F	128B

Notes:
1. When peripheral bus boot is selected, Peripheral bank 0 is automatically configured at reset to the address range listed above.
2. After the boot process, software may reassign the boot memory region for other uses.
3. All address ranges not listed above are reserved.

Table 2. DCR Address Map

Function	Start Address	End Address	Size
Total DCR Address Space[1]	0x000	0x3FF	1KW (4KB)[1]
Reserved	0x000	0x00F	16W
Memory Controller Registers	0x010	0x011	2W
External Bus Controller Registers	0x012	0x013	2W
Decompression Controller Registers	0x014	0x015	2W
Reserved	0x016	0x07F	106W
PLB Registers	0x080	0x08F	16W
Reserved	0x090	0x09F	16W
OPB Bridge Out Registers	0x0A0	0x0A7	8W
Reserved	0x0A8	0x0AF	8W
Clock, Control, and Reset	0x0B0	0x0B7	8W
Power Management	0x0B8	0x0BF	8W
Interrupt Controller	0x0C0	0x0CF	16W
Reserved	0x0D0	0x0FF	48W
DMA Controller Registers	0x100	0x13F	64W
Reserved	0x140	0x3FF	704W

Notes:
1. DCR address space is addressable with up to 10 bits (1024 or 1K unique addresses). Each unique address represents a single 32-bit (word) register, or 1 kiloword (KW) (which equals 4 KB).

SDRAM Memory Controller

The PPC405CR Memory Controller core provides a low latency access path to SDRAM memory. A variety of system memory configurations are supported. The memory controller supports up to four logical banks. Up to 256MB per bank are supported, up to a maximum of 1GB. Memory timings, address and bank sizes, and memory addressing modes are programmable.

Features include:

- 11x8 to 13x11 addressing for SDRAM (2- and 4-bank)
- 32-bit memory interface support
- Programmable address compare for each bank of memory
- Industry standard 168-pin DIMMS are supported (some configurations)
- 4MB to 256MB per bank
- Programmable address mapping and timing
- Auto refresh
- Page mode accesses with up to 4 open pages
- Power Management (self-refresh)
- Error Checking and Correction (ECC) support
  - Standard SEC/DED coverage
  - Aligned nibble error detect
  - Address error logging

External Peripheral Bus Controller (EBC)

- Supports eight banks of ROM, EPROM, SRAM, Flash memory, or slave peripheral I/O
- Up to 66MHz operation
- Burst and non-burst devices
- 8-, 16-, 32-bit byte-addressable data bus width support
- Programmable 2K clock time-out counter with disable for Ready
- Programmable access timing per device
  - 0–255 wait states for non-burst devices
  - 0–31 burst wait states for first access and up to 7 wait states for subsequent accesses
  - Programmable CSon, CSoff relative to address
  - Programmable OEon, WEon, WEoff (0 to 3 clock cycles) relative to CS
- Programmable address mapping
- Peripheral device pacing with external “Ready”
- External master interface
  - Write posting from external master
  - Read prefetching on PLB for external master reads
  - Bursting capable from external master
  - Allows external master access to all non-EBC PLB slaves
  - External master can control EBC slaves for own access and control

DMA Controller

- Supports the following transfers:
  - Memory-to-memory transfers
  - Buffered peripheral to memory transfers

- Buffered memory to peripheral transfers
- Four channels
- Scatter/Gather capability for programming multiple DMA operations
- 8-, 16-, 32-bit peripheral support (OPB and external)
- 32-bit addressing
- Address increment or decrement
- Internal 32-byte data buffering capability
- Supports internal and external peripherals
- Support for memory mapped peripherals
- Support for peripherals running on slower frequency buses

UART

- One 8-pin UART and one 4-pin UART interface provided
- Selectable internal or external serial clock to allow wide range of baud rates
- Register compatibility with NS16550 register set
- Complete status reporting capability
- Transmitter and receiver are each buffered with 16-byte FIFOs when in FIFO mode
- Fully programmable serial-interface characteristics
- Supports DMA using internal DMA engine

IIC Bus Interface

- Compliant with Phillips® Semiconductors I^2C Specification, dated 1995
- Operation at 100 kHz or 400 kHz
- 8-bit data
- 10- or 7-bit address
- Slave transmitter and receiver
- Master transmitter and receiver
- Multiple bus masters
- Supports fixed V_{DD} IIC interface
- Two independent 4 x 1 byte data buffers
- Twelve memory-mapped, fully programmable configuration registers
- One programmable interrupt request signal
- Provides full management of all IIC bus protocol
- Programmable error recovery

General Purpose IO (GPIO) Controller

- Controller functions and GPIO registers are programmed and accessed via memory-mapped OPB bus master accesses.
- All GPIOs are pin-shared with other functions. DCRs control whether a particular pin that has GPIO capabilities acts as a GPIO or is used for another purpose. The 23 GPIOs are multiplexed with:
  - 7 of 8 chip selects.
  - All seven external interrupts.
  - All nine instruction trace pins.
- Each GPIO output is separately programmable to emulate an open-drain driver (two states, drive to zero or open circuit).

Universal Interrupt Controller (UIC)

The Universal Interrupt Controller (UIC) provides the control, status, and communications necessary between the various sources of interrupts and the local PowerPC processor.

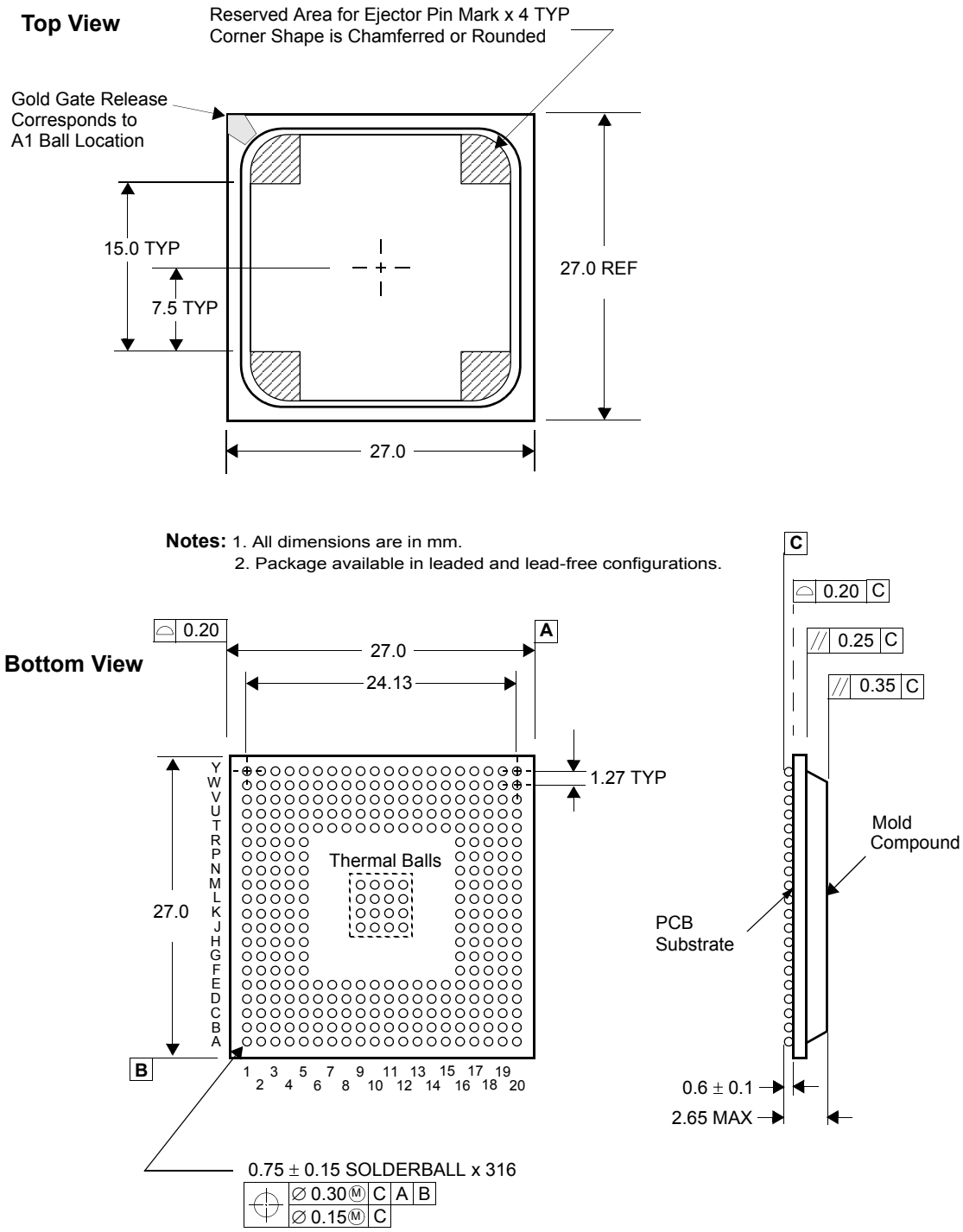
Features include:

- Supports 7 external and 10 internal interrupts
- Edge triggered or level-sensitive
- Positive or negative active
- Non-critical or critical interrupt to PPC405 processor core
- Programmable critical interrupt priority ordering
- Programmable critical interrupt vector for faster vector processing

JTAG

- IEEE 1149.1 test access port
- IBM RISCWatch debugger support
- JTAG Boundary Scan Description Language (BSDL)

Figure 2. 27mm, 316-Ball E-PBGA Package



Pin Lists

In this section there are two tables that correlate the external signals to the physical package pin (ball) on which they appear.

The following table lists all the external signals in alphabetical order and shows the ball number on which the signal appears. Multiplexed signals are shown with the default signal (following reset) *not* in brackets and the alternate signal in brackets. The page number listed gives the page in "Signal Functional Description" on page 23 where the signals in the indicated interface group begin.

Table 3. Signals Listed Alphabetically (Sheet 1 of 7)

Signal Name	Ball	Interface Group	Page
AV_{DD}	E20	Power	27
BA0 BA1	J17 H18	SDRAM	23
$\overline{\text{BankSel0}}$ $\overline{\text{BankSel1}}$ $\overline{\text{BankSel2}}$ $\overline{\text{BankSel3}}$	L19 N17 P17 U19	SDRAM	23
BusReq	P2	External Master Peripheral	25
$\overline{\text{CAS}}$	K17	SDRAM	23
ClkEn0 ClkEn1	J19 G20	SDRAM	23
DMAAck0 DMAAck1 DMAAck2 DMAAck3	C16 B17 B16 A14	External Slave Peripheral	23
DMAReq0 DMAReq1 DMAReq2 DMAReq3	A19 C15 B15 A8	External Slave Peripheral	23
DQM0 DQM1 DQM2 DQM3	U18 W14 Y10 U8	SDRAM	23
DQMCB	V19	SDRAM	23
DrvrInh1 DrvrInh2	F17 C19	System	26
ECC0 ECC1 ECC2 ECC3 ECC4 ECC5 ECC6 ECC7	V17 Y18 U14 V13 Y13 V12 W11 V11	SDRAM	23
EOT0/TC0 EOT1/TC1 EOT2/TC2 EOT3/TC3	G4 F2 W1 Y2	External Slave Peripheral	23
$\overline{\text{ExtAck}}$ $\overline{\text{ExtReq}}$ $\overline{\text{ExtReset}}$	U5 Y3 P4	External Master Peripheral	25

Table 3. Signals Listed Alphabetically (Sheet 2 of 7)

Signal Name	Ball	Interface Group	Page
GND	A1 A6 A10 A15 A20 B2 B19 C3 C18 D4 D17 E5 E10 E11 E16 F1 F20 J9 J10 J11 J12 K5 K9 K10 K11 K12 K16 K20 L1 L5 L9 L10 L11 L12 L16 M9 M10 M11 M12 R1 R20	Power **Note:** J9–J12, K9–K12, L9–L12, and M9–M12 are also thermal balls.	27
GND (cont)	T5 T10 T11 T16 U4 U17 V3 V18 W2 W19 Y1 Y6 Y11 Y15 Y20	Power	27

Table 3. Signals Listed Alphabetically (Sheet 3 of 7)

Signal Name	Ball	Interface Group	Page
GPIO1[TS1E] GPIO2[TS2E] GPIO3[TS1O] GPIO4[TS2O] GPIO5[TS3] GPIO6[TS4] GPIO7[TS5] GPIO8[TS6] GPIO9[TrcClk]	B18 D16 C17 P18 T17 W18 Y19 W13 V6	System	26
$\overline{\text{Halt}}$	E19	System	26
HoldAck HoldPri HoldReq	T4 T3 V2	External Master Peripheral	25
IICSCL	U15	Internal Peripheral	25
IICSDA	W17	Internal Peripheral	25
IRQ0[GPIO17] IRQ1[GPIO18] IRQ2[GPIO19] IRQ3[GPIO20] IRQ4[GPIO21] IRQ5[GPIO22] IRQ6[GPIO23]	D18 C20 E18 D20 G17 F18 W20	Interrupts	26
MemAddr0 MemAddr1 MemAddr2 MemAddr3 MemAddr4 MemAddr5 MemAddr6 MemAddr7 MemAddr8 MemAddr9 MemAddr10 MemAddr11 MemAddr12	Y7 W7 V8 U7 Y4 U6 W4 V5 W3 V4 U3 V1 T2	SDRAM **Note:** During a $\overline{\text{CAS}}$ cycle MemAddr0 is the least significant bit (lsb) on this bus.	23
MemClkOut0 MemClkOut1	H20 G18	SDRAM	23

Table 3. Signals Listed Alphabetically (Sheet 4 of 7)

Signal Name	Ball	Interface Group	Page
MemData0	J18	SDRAM **Note:** MemData0 is the most significant bit (msb) on this bus.	23
MemData1	K19		
MemData2	L20		
MemData3	M20		
MemData4	M19		
MemData5	L18		
MemData6	L17		
MemData7	N20		
MemData8	N19		
MemData9	M18		
MemData10	M17		
MemData11	P20		
MemData12	P19		
MemData13	N18		
MemData14	U20		
MemData15	T18		
MemData16	W16		
MemData17	Y17		
MemData18	Y16		
MemData19	V14		
MemData20	Y14		
MemData21	U12		
MemData22	W12		
MemData23	Y12		
MemData24	Y9		
MemData25	W9		
MemData26	V10		
MemData27	U10		
MemData28	Y8		
MemData29	W8		
MemData30	V9		
MemData31	U9		
OV_{DD}	F5 G5 P5 R5 T6 T7 T14 T15 F16 G16 P16 R16 E6 E7 E14 E15	Power	27

Table 3. Signals Listed Alphabetically (Sheet 5 of 7)

Signal Name	Ball	Interface Group	Page
PerAddr0	A3	External Slave Peripheral **Note:** PerAddr0 is the most significant bit (msb) on this bus.	23
PerAddr1	A4		
PerAddr2	B6		
PerAddr3	D7		
PerAddr4	C6		
PerAddr5	B7		
PerAddr6	D8		
PerAddr7	C7		
PerAddr8	B8		
PerAddr9	A7		
PerAddr10	D9		
PerAddr11	C8		
PerAddr12	B9		
PerAddr13	D10		
PerAddr14	C9		
PerAddr15	A9		
PerAddr16	B11		
PerAddr17	A11		
PerAddr18	B12		
PerAddr19	D11		
PerAddr20	A13		
PerAddr21	B13		
PerAddr22	C12		
PerAddr23	D12		
PerAddr24	B14		
PerAddr25	C13		
PerAddr26	D13		
PerAddr27	A16		
PerAddr28	C14		
PerAddr29	D14		
PerAddr30	A17		
PerAddr31	D15		
$\overline{\text{PerBLast}}$	E2	External Slave Peripheral	23
PerClk	D3	External Master Peripheral	25
$\overline{\text{PerCS0}}$	D6	External Slave Peripheral	23
$\overline{\text{PerCS1}}$[GPIO10]	B5		
$\overline{\text{PerCS2}}$[GPIO11]	C5		
$\overline{\text{PerCS3}}$[GPIO12]	A5		
$\overline{\text{PerCS4}}$[GPIO13]	B10		
$\overline{\text{PerCS5}}$[GPIO14]	C10		
$\overline{\text{PerCS6}}$[GPIO15]	A12		
$\overline{\text{PerCS7}}$[GPIO16]	C11		

Table 3. Signals Listed Alphabetically (Sheet 6 of 7)

Signal Name	Ball	Interface Group	Page
PerData0 PerData1 PerData2 PerData3 PerData4 PerData5 PerData6 PerData7 PerData8 PerData9 PerData10 PerData11 PerData12 PerData13 PerData14 PerData15 PerData16 PerData17 PerData18 PerData19 PerData20 PerData21 PerData22 PerData23 PerData24 PerData25 PerData26 PerData27 PerData28 PerData29 PerData30 PerData31	U2 R4 U1 R2 R3 T1 N4 P3 N2 P1 M4 N3 M2 N1 L4 M3 L2 M1 K2 L3 K1 J1 J2 K3 K4 H1 H2 J3 J4 G1 G2 H3	External Slave Peripheral **Note:** PerData0 is the most significant bit (msb) on this bus.	23
PerErr	B1	External Master Peripheral	25
$\overline{\text{PerOE}}$	E4	External Slave Peripheral	23
PerPar0 PerPar1 PerPar2 PerPar3	C2 G3 E1 H4	External Slave Peripheral	23
PerReady	E3	External Slave Peripheral	23
PerR/$\overline{\text{W}}$	C1	External Slave Peripheral	23
$\overline{\text{PerWBE0}}$ $\overline{\text{PerWBE1}}$ $\overline{\text{PerWBE2}}$ $\overline{\text{PerWBE3}}$	D2 F4 F3 D1	External Slave Peripheral	23
$\overline{\text{PerWE}}$	C4	External Slave Peripheral	23
$\overline{\text{RAS}}$	K18	SDRAM	23
RcvrInh	E17	System	26
Reserved	J20 G19 R17 T20 V16	Other pins **Notes:** 1. Connect G19 to ground. 2. Other reserved pins are not connected internally within the chip and should not have signals, voltage, or ground applied to them.	27

Table 3. Signals Listed Alphabetically (Sheet 7 of 7)

Signal Name	Ball	Interface Group	Page
SysClk SysErr SysReset	H17 A18 D19	System	26
TCK TDI TDO	B4 A2 D5	JTAG	26
TestEn	F19	System	26
TmrClk	B20	System	26
TMS	B3	JTAG	26
TRST	H19	JTAG	26
UART0_CTS UART0_DCD UART0_DSR UART0_DTR UART0_RI UART0_RTS UART0_Rx UART0_Tx	W10 R18 U16 U13 V15 V20 T19 W15	Internal Peripheral	25
UART1_DSR[UART1_CTS] UART1_RTS[UART1_DTR] UART1_Rx UART1_Tx	V7 W6 W5 Y5	Internal Peripheral	25
UARTSerClk	R19	Internal Peripheral	25
V_{DD}	E8 E9 E12 E13 H5 H16 J5 J16 M5 M16 N5 N16 T8 T9 T12 T13	Power	27
WE	U11	SDRAM	23

Table 4. Signals Listed by Ball Assignment (Sheet 1 of 3)

Ball	Signal Name	Ball	Signal Name	Ball	Signal Name	Ball	Signal Name
A1	GND	B10	PerCS4[GPIO13]	C19	DrvrInh2	E8	V_{DD}
A2	TDI	B11	PerAddr16	C20	IRQ1[GPIO18]	E9	V_{DD}
A3	PerAddr0	B12	PerAddr18	D1	PerWBE3	E10	GND
A4	PerAddr1	B13	PerAddr21	D2	PerWBE0	E11	GND
A5	PerCS3[GPIO12]	B14	PerAddr24	D3	PerClk	E12	V_{DD}
A6	Gnd	B15	DMAReq2	D4	GND	E13	V_{DD}
A7	PerAddr9	B16	DMAAck2	D5	TDO	E14	OV_{DD}
A8	DMAReq3	B17	DMAAck1	D6	PerCS0	E15	OV_{DD}
A9	PerAddr15	B18	GPIO1[TS1E]	D7	PerAddr3	E16	GND
A10	GND	B19	GND	D8	PerAddr6	E17	Rcrvinh
A11	PerAddr17	B20	TmrClk	D9	PerAddr10	E18	IRQ2[GPIO19]
A12	PerCS6[GPIO15]	C1	PerR/W	D10	PerAddr13	E19	Halt
A13	PerAddr20	C2	PerPar0	D11	PerAddr19	E20	AV_{DD}
A14	DMAAck3	C3	GND	D12	PerAddr23	F1	GND
A15	GND	C4	PerWE	D13	PerAdd26	F2	EOT1/TC1
A16	PerAddr27	C5	PerCS2[GPIO11]	D14	PerAddr29	F3	PerWBE2
A17	PerAddr30	C6	PerAddr4	D15	PerAddr31	F4	PerWBE1
A18	SysErr	C7	PerAddr7	D16	GPIO2[TS2E]	F5	OV_{DD}
A19	DMAReq0	C8	PerAddr11	D17	GND	F16	OV_{DD}
A20	GND	C9	PerAddr14	D18	IRQ0[GPIO17]	F17	DrvrInh1
B1	PerErr	C10	PerCS5[GPIO14]	D19	SysReset	F18	IRQ5[GPIO22]
B2	GND	C11	PerCS7[GPIO16]	D20	IRQ3[GPIO20]	F19	TestEn
B3	TMS	C12	PerAddr22	E1	PerPar2	F20	GND
B4	TCK	C13	PerAddr25	E2	PerBLast	G1	PerData29
B5	PerCS1[GPIO10]	C14	PerAddr28	E3	PerReady	G2	PerData30
B6	PerAddr2	C15	DMAReq1	E4	PerOE	G3	PerPar1
B7	PerAddr5	C16	DMAAck0	E5	GND	G4	EOT0/TC0
B8	PerAddr8	C17	GPIO3[TS1O]	E6	OV_{DD}	G5	OV_{DD}
B9	PerAddr12	C18	GND	E7	OV_{DD}	G16	OV_{DD}

Table 4. Signals Listed by Ball Assignment (Sheet 2 of 3)

Ball	Signal Name	Ball	Signal Name	Ball	Signal Name	Ball	Signal Name
G17	IRQ4[GPIO21]	K2	PerData18	M3	PerData15	P18	GPIO4[TS2O]
G18	MemClkOut1	K3	PerData23	M4	PerData10	P19	MemData12
G19	Reserved	K4	PerData24	M5	V_{DD}	P20	MemData11
G20	ClkEn1	K5	GND	M9	Thermal Ball	R1	GND
H1	PerData25	K9	Thermal Ball	M10	Thermal Ball	R2	PerData3
H2	PerData26	K10	Thermal Ball	M11	Thermal Ball	R3	PerData4
H3	PerData31	K11	Thermal Ball	M12	Thermal Ball	R4	PerData1
H4	PerPar3	K12	Thermal Ball	M16	V_{DD}	R5	OV_{DD}
H5	V_{DD}	K16	GND	M17	MemData10	R16	OV_{DD}
H16	V_{DD}	K17	$\overline{CAS}$	M18	MemData9	R17	Reserved
H17	SysClk	K18	$\overline{RAS}$	M19	MemData4	R18	$\overline{UART0_DCD}$
H18	BA1	K19	MemData1	M20	MemData3	R19	UARTSerClk
H19	$\overline{TRST}$	K20	GND	N1	PerData13	R20	GND
H20	MemClkOut0	L1	GND	N2	PerData8	T1	PerData5
J1	PerData21	L2	PerData16	N3	PerData11	T2	MemAddr12
J2	PerData22	L3	PerData19	N4	PerData6	T3	HoldPri
J3	PerData27	L4	PerData14	N5	V_{DD}	T4	HoldAck
J4	PerData28	L5	GND	N16	V_{DD}	T5	GND
J5	V_{DD}	L9	Thermal Ball	N17	$\overline{BankSel1}$	T6	OV_{DD}
J9	Thermal Ball	L10	Thermal Ball	N18	MemData13	T7	OV_{DD}
J10	Thermal Ball	L11	Thermal Ball	N19	MemData8	T8	V_{DD}
J11	Thermal Ball	L12	Thermal Ball	N20	MemData7	T9	V_{DD}
J12	Thermal Ball	L16	GND	P1	PerData9	T10	GND
J16	V_{DD}	L17	MemData6	P2	BusReq	T11	GND
J17	BA0	L18	MemData5	P3	PerData7	T12	V_{DD}
J18	MemData0	L19	$\overline{BankSel0}$	P4	$\overline{ExtReset}$	T13	V_{DD}
J19	ClkEn0	L20	MemData2	P5	OV_{DD}	T14	OV_{DD}
J20	Reserved	M1	PerData17	P16	OV_{DD}	T15	OV_{DD}
K1	PerData20	M2	PerData12	P17	$\overline{BankSel2}$	T16	GND

Table 4. Signals Listed by Ball Assignment (Sheet 3 of 3)

Ball	Signal Name	Ball	Signal Name	Ball	Signal Name	Ball	Signal Name
T17	GPIO5[TS3]	U18	DQM0	V19	DQMCB	W20	IRQ6[GPIO23]
T18	MemData15	U19	$\overline{\text{BankSel3}}$	V20	$\overline{\text{UART0_RTS}}$	Y1	GND
T19	UART0_RX	U20	MemData14	W1	EOT2/TC2	Y2	EOT3/TC3
T20	Reserved	V1	MemAddr11	W2	GND	Y3	$\overline{\text{ExtReq}}$
U1	PerData2	V2	HoldReq	W3	MemAddr8	Y4	MemAddr4
U2	PerData0	V3	GND	W4	MemAddr6	Y5	UART1_TX
U3	MemAddr10	V4	MemAddr9	W5	UART1_RX	Y6	GND
U4	GND	V5	MemAddr7	W6	$\overline{\text{UART1_RTS}}$ [$\overline{\text{UART1_DTR}}$]	Y7	MemAddr0
U5	$\overline{\text{ExtAck}}$	V6	GPIO9[TrcClk]	W7	MemAddr1	Y8	MemData28
U6	MemAddr5	V7	$\overline{\text{UART1_DSR}}$ [$\overline{\text{UART1_CTS}}$]	W8	MemData29	Y9	MemData24
U7	MemAddr3	V8	MemAddr2	W9	MemData25	Y10	DQM2
U8	DQM3	V9	MemData30	W10	$\overline{\text{UART0_CTS}}$	Y11	GND
U9	MemData31	V10	MemData26	W11	ECC6	Y12	MemData23
U10	MemData27	V11	ECC7	W12	MemData22	Y13	ECC4
U11	$\overline{\text{WE}}$	V12	ECC5	W13	GPIO8[TS6]	Y14	MemData20
U12	MemData21	V13	ECC3	W14	DQM1	Y15	GND
U13	$\overline{\text{UART0_DTR}}$	V14	MemData19	W15	UART0_TX	Y16	MemData18
U14	ECC2	V15	$\overline{\text{UART0_RI}}$	W16	MemData16	Y17	MemData17
U15	IICSCL	V16	Reserved	W17	IICSDA	Y18	ECC1
U16	$\overline{\text{UART0_DSR}}$	V17	ECC0	W18	GPIO6[TS4]	Y19	GPIO7[TS5]
U17	GND	V18	GND	W19	GND	Y20	GND

Signal Descriptions

The PPC405CR embedded controller is packaged in a 316-ball enhanced plastic ball grid array (E-PBGA). The following table provides a summary of the number of package pins associated with each functional interface group.

Table 5. Pin Summary

Group	No. of Pins
SDRAM	71
External Peripheral	97
External Master	9
Internal Peripheral	15
Interrupts	7
JTAG	5
System	18
Total Signal Pins	**222**
AV_{DD}	1
OV_{DD}	16
V_{DD}	16
Gnd	40
Thermal (and Gnd)	16
Reserved	5
Total Pins	**316**

Multiplexed Pins

In the table “Signal Functional Description” on page 23, each I/O signal is listed along with a short description of the signal function. Some signals are multiplexed onto the same package pin (ball) so that the pin can be used for different functions. Multiplexed signals are shown as a default signal with a secondary signal in square brackets (for example, GPIO1[TS1E]). Active-low signals (for example, $\overline{RAS}$) are marked with an overline.

It is expected that in any single application a particular pin will always be programmed to serve the same function. The flexibility of multiplexing allows a single chip to offer a richer pin selection than would otherwise be possible.

In addition to multiplexing, many pins are also multi-purpose. For example, the EBC peripheral controller address pins are used as outputs by the PPC405CR to broadcast an address to external slave devices when the PPC405CR has control of the external bus. When during the course of normal chip operation an external master gains ownership of the external bus, these same pins are used as inputs which are driven by the external master and received by the EBC in the PPC405CR.

Intialization Strapping

One group of pins is used as strapped inputs during system reset. These pins function as strapped inputs only during reset and are used for other functions during normal operation (see “Strapping” on page 39). Note that these are *not multiplexed* pins since the function of the pins is not programmable.

Pull-Up and Pull-Down Resistors

Pull-up and pull-down resistors are used for strapping during reset and to retain unused or undriven inputs in an appropriate state. The recommended pull-up value of 3kΩ to +3.3V (10kΩ to +5V can be used on 5V tolerant I/Os) and pull-down value of 1kΩ to GND, applies only to individually terminated signals. To prevent possible damage to the device, I/Os capable of becoming outputs *must never* be tied together and terminated through a common resistor.

If your system-level test methodology permits, input-only signals can be connected together and terminated through either a common resistor or directly to +3.3V or GND. When a resistor is used, its value must ensure that the grouped I/Os reach a valid logic zero or logic one state when accounting for the total input current into the PPC405CR.

Unused I/Os

Strapping of some pins may be necessary when they are unused. Although the PPC405CR requires only the pull-up and pull-down terminations as specified in the "Signal Functional Description" on page 23, good design practice is to terminate all unused inputs or to configure I/Os such that they always drive. If unused, the peripheral and SDRAM buses should be configured and terminated as follows:

- Peripheral interface—PerAddr0:31, PerData0:31, and all of the control signals are driven by default. Terminate PerReady high and PerError low.
- SDRAM—Program SDRAM0_CFG[EMDULR]=1 and SDRAM0_CFG[DCE]=1. This causes the PPC405CR to actively drive all of the SDRAM address, data, and control signals.

External Bus Control Signals

All peripheral bus control signals ($\overline{\text{PerCS0:7}}$, PerR/$\overline{\text{W}}$, $\overline{\text{PerWBE0:3}}$, $\overline{\text{PerOE}}$, $\overline{\text{PerWE}}$, $\overline{\text{PerBLast}}$, HoldAck, $\overline{\text{ExtAck}}$) are set to the high-impedance state when $\overline{\text{ExtReset}}$=0. In addition, as detailed in the *PowerPC 405CR Embedded Processor User's Manual*, the peripheral bus controller can be programmed via EBC0_CFG to float some of these control signals between transactions and/or when an external master owns the peripheral bus. As a result, a pull-up resistor should be added to those control signals where an undriven state may affect any devices receiving that particular signal.

The following table lists all of the I/O signals provided by the PPC405CR. Please refer to "Signals Listed Alphabetically" on page 11 for the pin number to which each signal is assigned.

Table 6. Signal Functional Description (Sheet 1 of 5)

Multiplexed signals are shown in brackets following the first signal name assigned to each multiplexed ball.
Notes:
1. Receiver input has hysteresis.
2. Must pull up. See “Pull-Up and Pull-Down Resistors” on page 21 for recommended termination values.
3. Must pull down. See “Pull-Up and Pull-Down Resistors” on page 21 for recommended termination values.
4. If not used, must pull up.
5. If not used, must pull down.
6. Strapping input during reset; pull-up or pull-down required.
7. Pull-up may be required. See “External Bus Control Signals” on page 22.

Signal Name	Description	I/O	Type	Notes
SDRAM Interface				
MemData0:31	Memory Data bus. **Notes:** 1. MemData0 is the most significant bit (msb). 2. MemData31 is the least significant bit (lsb).	I/O	3.3V LVTTL	
MemAddr12:0	Memory Address bus. **Notes:** 1. MemAddr12 is the most significant bit (msb). 2. MemAddr0 is the least significant bit (lsb).	O	3.3V LVTTL	
BA0:1	Bank Address supporting up to four internal banks.	O	3.3V LVTTL	
$\overline{\text{RAS}}$	Row Address Strobe.	O	3.3V LVTTL	
$\overline{\text{CAS}}$	Column Address Strobe.	O	3.3V LVTTL	
DQM0:3	DQM for byte lanes 0 (MemData0:7), 1 (MemData8:15), 2 (MemData16:23), and 3 (MemData24:31).	O	3.3V LVTTL	
DQMCB	DQM for ECC check bits.	O	3.3V LVTTL	
ECC0:7	ECC check bits 0:7.	I/O	3.3V LVTTL	
$\overline{\text{BankSel0:3}}$	Select up to four external SDRAM banks.	O	3.3V LVTTL	
$\overline{\text{WE}}$	Write Enable.	O	3.3V LVTTL	
ClkEn0:1	SDRAM Clock Enable.	O	3.3V LVTTL	
MemClkOut0:1	Two copies of an SDRAM clock allows, in some cases, glueless SDRAM attach without requiring this signal to be repowered by a PLL or zero-delay buffer.	O	3.3V LVTTL	
External Slave Peripheral Interface				
PerData0:31	Peripheral data bus used by PPC405CR when not in external master mode, otherwise used by external master. **Note:** PerData0 is the most significant bit (msb) on this bus.	I/O	5V tolerant 3.3V LVTTL	1
PerAddr0:31	Peripheral address bus used by PPC405CR when not in external master mode, otherwise used by external master. **Note:** PerAddr0 is the most significant bit (msb) on this bus.	I/O	5V tolerant 3.3V LVTTL	1
PerPar0:3	Peripheral byte parity signals.	I/O	5V tolerant 3.3V LVTTL	1
$\overline{\text{PerWBE0:3}}$	As outputs, these pins can act as byte-enables which are valid for an entire cycle or as write-byte-enables which are valid for each byte on each data transfer, allowing partial word transactions. As outputs, pins are used by either peripheral controller or the DMA controller depending upon the type of transfer involved. Used as inputs when external bus master owns the external interface.	I/O	5V tolerant 3.3V LVTTL	1, 7
$\overline{\text{PerWE}}$	Peripheral write enable. Active when any of the four $\overline{\text{PerWBE0:3}}$ signals are active.	O	5V tolerant 3.3V LVTTL	

Table 6. Signal Functional Description (Sheet 2 of 5)

Multiplexed signals are shown in brackets following the first signal name assigned to each multiplexed ball.
Notes:
1. Receiver input has hysteresis.
2. Must pull up. See “Pull-Up and Pull-Down Resistors” on page 21 for recommended termination values.
3. Must pull down. See “Pull-Up and Pull-Down Resistors” on page 21 for recommended termination values.
4. If not used, must pull up.
5. If not used, must pull down.
6. Strapping input during reset; pull-up or pull-down required.
7. Pull-up may be required. See “External Bus Control Signals” on page 22.

Signal Name	Description	I/O	Type	Notes
$\overline{\text{PerCS0}}$	Peripheral chip select bank 0.	O	5V tolerant 3.3V LVTTL	7
$\overline{\text{PerCS1:7}}$[GPIO10:16]	Seven additional peripheral chip selects or General Purpose I/O. To access this function, software must toggle a DCR register bit.	O[I/O]	5V tolerant 3.3V LVTTL	1, 7
$\overline{\text{PerOE}}$	Used by either peripheral controller or DMA controller depending upon the type of transfer involved. When the PPC405CR is the bus master, it enables the selected device to drive the bus.	O	5V tolerant 3.3V LVTTL	7
PerR/$\overline{\text{W}}$	Used by the PPC405CR when not in external master mode, as output by either the peripheral controller or DMA controller depending upon the type of transfer involved. High indicates a read from memory, low indicates a write to memory. Otherwise it used by the external master as an input to indicate the direction of transfer.	I/O	5V tolerant 3.3V LVTTL	1
PerReady	Used by a peripheral slave to indicate it is ready to transfer data.	I	5V tolerant 3.3V LVTTL	1
$\overline{\text{PerBLast}}$	Used by the PPC405CR when not in external master mode, otherwise used by external master. Indicates the last transfer of a memory access.	I/O	5V tolerant 3.3V LVTTL	1, 7
DMAReq0:3	DMAReq0:3 are used by slave peripherals to indicate they are prepared to transfer data.	I	5V tolerant 3.3V LVTTL	1
DMAAck0:3	DMAAck0:3 are used by the PPC405CR to indicate that data transfers have occurred.	O	5V tolerant 3.3V LVTTL	6
EOT0:3/TC0:3	End Of Transfer/Terminal Count.	I/O	5V tolerant 3.3V LVTTL	1

Table 6. Signal Functional Description (Sheet 3 of 5)

Multiplexed signals are shown in brackets following the first signal name assigned to each multiplexed ball.
Notes:
1. Receiver input has hysteresis.
2. Must pull up. See “Pull-Up and Pull-Down Resistors” on page 21 for recommended termination values.
3. Must pull down. See “Pull-Up and Pull-Down Resistors” on page 21 for recommended termination values.
4. If not used, must pull up.
5. If not used, must pull down.
6. Strapping input during reset; pull-up or pull-down required.
7. Pull-up may be required. See “External Bus Control Signals” on page 22.

Signal Name	Description	I/O	Type	Notes
External Master Peripheral Interface				
PerClk	Peripheral clock to be used by an external master and by synchronous peripheral slaves.	O	5V tolerant 3.3V LVTTL	
$\overline{\text{ExtReset}}$	Peripheral reset to be used by an external master and by synchronous peripheral slaves.	O	5V tolerant 3.3V LVTTL	
HoldReq	Hold Request, used by an external master to request ownership of the peripheral bus.	I	5V tolerant 3.3V LVTTL	1, 5
HoldAck	Hold Acknowledge, used by the PPC405CR to transfer ownership of peripheral bus to an external master.	O	5V tolerant 3.3V LVTTL	6
$\overline{\text{ExtReq}}$	$\overline{\text{ExtReq}}$ is used by an external master to indicate it is prepared to transfer data.	I	5V tolerant 3.3V LVTTL	1
$\overline{\text{ExtAck}}$	$\overline{\text{ExtAck}}$ is used by the PPC405CR to indicate a data transfer cycle.	O	5V tolerant 3.3V LVTTL	6
HoldPri	Used by an external master to indicate the priority of a given external master tenure.	I	5V tolerant 3.3V LVTTL	1
BusReq	Used when the PPC405CR needs to regain control of the peripheral interface from an external master.	O	5V tolerant 3.3V LVTTL	
PerErr	Used as an input to indicate that an external slave peripheral error has occurred.	I	5V tolerant 3.3V LVTTL	1, 5
Internal Peripheral Interface				
UARTSerClk	Serial clock. Used to provide an alternate clock to the internally generated serial clock. Used in cases where the allowable internally generated baud rates are not satisfactory. This input can be individually connected to either UART.	I	5V tolerant 3.3V LVTTL	1
UART0_Rx	UART0 Receive (serial data in).	I	5V tolerant 3.3V LVTTL	1
UART0_Tx	UART0 Transmit (serial data out).	O	5V tolerant 3.3V LVTTL	6
$\overline{\text{UART0_DCD}}$	UART0 Data Carrier Detect.	I	5V tolerant 3.3V LVTTL	1
$\overline{\text{UART0_DSR}}$	UART0 Data Set Ready.	I	5V tolerant 3.3V LVTTL	1
$\overline{\text{UART0_CTS}}$	UART0 Clear To Send.	I	5V tolerant 3.3V LVTTL	1
$\overline{\text{UART0_DTR}}$	UART0 Data Terminal Ready.	O	5V tolerant 3.3V LVTTL	6
$\overline{\text{UART0_RTS}}$	UART0 Request To Send.	O	5V tolerant 3.3V LVTTL	6
$\overline{\text{UART0_RI}}$	UART0 Ring Indicator.	I	5V tolerant 3.3V LVTTL	1
UART1_Rx	UART1 Receive (serial data in).	I	5V tolerant 3.3V LVTTL	1

Table 6. Signal Functional Description (Sheet 4 of 5)

Multiplexed signals are shown in brackets following the first signal name assigned to each multiplexed ball.
Notes:
1. Receiver input has hysteresis.
2. Must pull up. See "Pull-Up and Pull-Down Resistors" on page 21 for recommended termination values.
3. Must pull down. See "Pull-Up and Pull-Down Resistors" on page 21 for recommended termination values.
4. If not used, must pull up.
5. If not used, must pull down.
6. Strapping input during reset; pull-up or pull-down required.
7. Pull-up may be required. See "External Bus Control Signals" on page 22.

Signal Name	Description	I/O	Type	Notes
UART1_Tx	UART1 Transmit (serial data out).	O	5V tolerant 3.3V LVTTL	6
$\overline{\text{UART1_DSR}}$/ [UART1_CTS]	UART1 Data Set Ready or UART1 Clear To Send. To access this function, software must toggle a DCR register bit.	I	5V tolerant 3.3V LVTTL	1
$\overline{\text{UART1_RTS}}$/ [UART1_DTR]	UART1 Request To Send or UART1 Data Terminal Ready. To access this function, software must toggle a DCR register bit.	O	5V tolerant 3.3V LVTTL	6
IICSCL	IIC serial clock.	I/O	5V tolerant 3.3V LVTTL	1, 2
IICSDA	IIC serial data.	I/O	5V tolerant 3.3V LVTTL	1, 2
Interrupts Interface				
IRQ0:6[GPIO17:23]	Interrupt requests or General Purpose I/O. To access this function, software must toggle a DCR register bit.	I[I/O]	5V tolerant 3.3V LVTTL	1
JTAG Interface				
TDI	Test data in.	I	5V tolerant 3.3V LVTTL	1, 4
TMS	JTAG test mode select.	I	5V tolerant 3.3V LVTTL	1, 4
TDO	Test data out.	O	5V tolerant 3.3V LVTTL	
TCK	JTAG test clock. The frequency of this input can range from DC to 25MHz.	I	5V tolerant 3.3V LVTTL	1, 4
$\overline{\text{TRST}}$	JTAG reset. $\overline{\text{TRST}}$ must be low at power-on to initialize the JTAG controller and for normal operation of the PPC405CR.	I	5V tolerant 3.3V LVTTL	5
System Interface				
SysClk	Main system clock input.	I	5V tolerant 3.3V LVTTL	
$\overline{\text{SysReset}}$	Main system reset. External logic can drive this bidirectional pin low (minimum of 16 cycles) to initiate a system reset. A system reset can also be initiated by software. Implemented as an open-drain output (two states, 0 or open circuit).	I/O	5V tolerant 3.3V LVTTL	1, 2
SysErr	Set to 1 when a Machine Check is generated.	O	5V tolerant 3.3V LVTTL	
$\overline{\text{Halt}}$	Halt from external debugger.	I	5V tolerant 3.3V LVTTL	1, 2

Table 6. Signal Functional Description (Sheet 5 of 5)

Multiplexed signals are shown in brackets following the first signal name assigned to each multiplexed ball.
Notes:
1. Receiver input has hysteresis.
2. Must pull up. See "Pull-Up and Pull-Down Resistors" on page 21 for recommended termination values.
3. Must pull down. See "Pull-Up and Pull-Down Resistors" on page 21 for recommended termination values.
4. If not used, must pull up.
5. If not used, must pull down.
6. Strapping input during reset; pull-up or pull-down required.
7. Pull-up may be required. See "External Bus Control Signals" on page 22.

Signal Name	Description	I/O	Type	Notes
GPIO1[TS1E] GPIO2[TS2E]	General Purpose I/O or Even Trace execution status. To access this function, software must toggle a DCR register bit.	I/O[O]	5V tolerant 3.3V LVTTL	1, 6
GPIO3[TS1O] GPIO4[TS2O]	General Purpose I/O or Odd Trace execution status. To access this function, software must toggle a DCR register bit.	I/O[O]	5V tolerant 3.3V LVTTL	1, 6
GPIO5:8[TS3:6]	General Purpose I/O Trace status. To access this function, software must toggle a DCR register bit.	I/O[O]	5V tolerant 3.3V LVTTL	1
GPIO9[TrcClk]	General Purpose I/O or Trace interface clock. A toggling signal that is always half of the CPU core frequency. To access this function, software must toggle a DCR register bit.	I/O[O]	5V tolerant 3.3V LVTTL	1
TestEn	Test Enable.	I	2.5V CMOS w/pull-down	
RcvrInh	Receiver Inhibit. Used only for manufacturing tests. Pull up for normal operation.	I	5V tolerant 3.3V LVTTL	2
DrvrInh1:2	Driver Inhibit 1 and 2. Used only for manufacturing tests. Pull up for normal operation.	I	5V tolerant 3.3V LVTTL	2
TmrClk	An external clock input than can be used as an alternative to SysClk to run the CPU core. Which clock input is used is determined by software settings.	I	5V tolerant 3.3V LVTTL	1
Power				
GND	Ground **Note:** Pins J9–J12, K9–K12, L9–L12, and M9–M12 are also thermal balls.			
AV_{DD}	Filtered voltage input for PLL (analog) circuits			
OV_{DD}	Output driver voltage—3.3V			
V_{DD}	Logic voltage—2.5V			
Other pins				
Reserved	Connect G19 to GND. Do not connect signals, voltage, or ground to any other reserved pins.			

Table 7. Absolute Maximum Ratings

The absolute maximum ratings below are stress ratings only. Operation at or beyond these maximum ratings can cause permanent damage to the device

Characteristic	Symbol	Value	Unit
Supply Voltage (Internal Logic)	V_{DD}	0 to +2.7	V
Supply Voltage (I/O Interface)	OV_{DD}	0 to +3.6	V
PLL Supply Voltage	AV_{DD}	0 to +2.7	V
Input Voltage (2.5V CMOS receivers)	V_{IN}	-0.6 to V_{DD}+0.6	V
Input Voltage (3.3V LVTTL receivers)	V_{IN}	-0.6 to OV_{DD}+0.6	V
Input Voltage (5.0V LVTTL receivers)	V_{IN}	-0.6 to OV_{DD}+2.4	V
Storage Temperature Range	T_{STG}	-55 to +150	°C
Case temperature under bias	T_C	-40 to +120	°C

Note: All specified voltages are with respect to GND.

Figure 3. Package Thermal Specifications

The PPC405CR is designed to operate within a case temperature range of -40°C to +85°C. Thermal resistance values for the E-PBGA package in a convection environment are as follows:

Thermal Resistance	Symbol	Airflow ft/min (m/sec)			Unit
		0 (0)	100 (0.51)	200 (1.02)	
Junction-to-case	θ_{JC}	2	2	2	°C/W
Case-to-ambient [1]	θ_{CA}	18	16	15	°C/W

Notes:

1. For a chip mounted on a JEDEC 2S2P card without a heat sink.
2. For a chip mounted on a card with at least one signal and two power planes, the following relationships exist:
   a. Case temperature, T_C, is measured at top center of case surface with device soldered to circuit board.
   b. $T_A = T_C - P \times \theta_{CA}$, where T_A is ambient temperature and P is power consumption.
   c. $T_{CMax} = T_{JMax} - P \times \theta_{JC}$, where T_{JMax} is maximum junction temperature and P is power consumption.

Table 8. Recommended DC Operating Conditions

Device operation beyond the conditions specified is not recommended. Extended operation beyond the recommended conditions can affect device reliability.

Parameter	Symbol	Minimum	Typical	Maximum	Unit	Notes
Logic Supply Voltage	V_{DD}	+2.3	+2.5	+2.7	V	
I/O Supply Voltage	OV_{DD}	+3.0	+3.3	+3.6	V	
PLL Supply Voltage	AV_{DD}	+2.3	+2.5	+2.7	V	
Input Logic High (2.5V CMOS receivers)	V_{IH}	+1.7		V_{DD}	V	
Input Logic High (3.3V LVTTL receivers)	V_{IH}	+2.0		OV_{DD}	V	
Input Logic High (5.0V LVTTL receivers)	V_{IH}	+2.0		+5.0	V	
Input Logic Low (2.5V CMOS receivers)	V_{IL}	0		+0.7	V	
Input Logic Low (3.3/5.0V LVTTL receivers)	V_{IL}	0		+0.8	V	
Output Logic High	V_{OH}	+2.4		OV_{DD}	V	
Output Logic Low	V_{OL}	0		+0.4	V	
3.3V I/O Input Current (no pull-up or pull-down)	I_{IL1}			±10	µA	
Input Current (with internal pull-down)	I_{IL2}	±10 (@ 0V)		+400 (@ V_{DD})	µA	
5V Tolerant I/O Input Current [1]	I_{IL4}	±10		-650	µA	
Input Max Allowable Overshoot (2.5V CMOS receivers)	V_{IMAO25}			V_{DD} + 0.6	V	
Input Max Allowable Overshoot (3.3V LVTTL receivers)	V_{IMAO3}			OV_{DD} + 0.6	V	
Input Max Allowable Overshoot (5.0V LVTTL receivers)	V_{IMAO5}			+5.5	V	
Input Max Allowable Undershoot	V_{IMAU}	-0.6			V	
Output Max Allowable Overshoot	V_{OMAO}			OV_{DD} + 0.3	V	
Output Max Allowable Undershoot	V_{OMAU3}	-0.6			V	
Case Temperature	T_C	-40		+85	°C	

Notes:

1. See “5V-Tolerant I/O Input Current” on page 30

Figure 4. 5V-Tolerant I/O Input Current

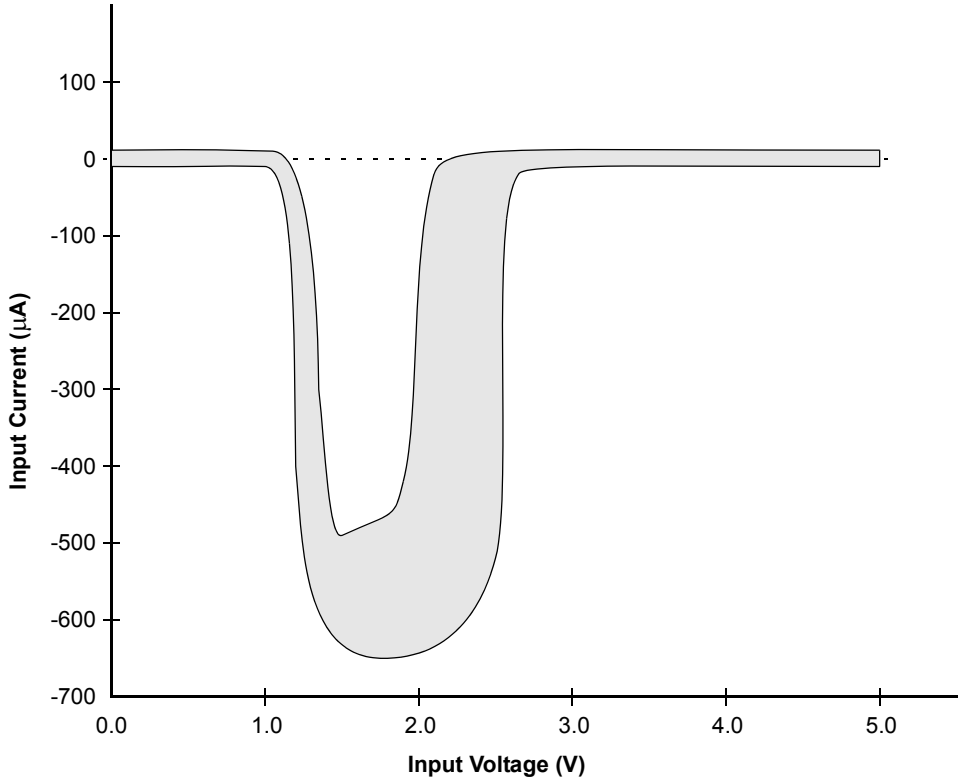


Table 9. Input Capacitance

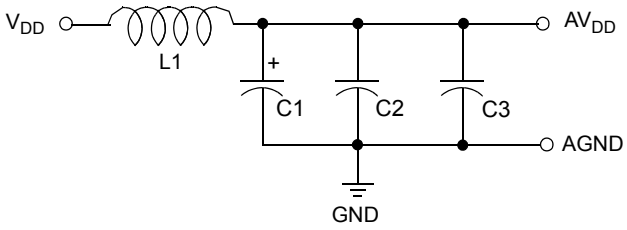
Parameter	Symbol	Maximum	Unit	Notes
3.3V LVTTL I/O	C_{IN1}	5.4	pF	
5V tolerant LVTTL I/O	C_{IN2}	4.4	pF	
RX only pins	C_{IN4}	3.4	pF	

Table 10. DC Electrical Characteristics

Parameter	Symbol	Minimum	Typical	Maximum	Unit
Active Operating Current (V_{DD})—133MHz	I_{DD}		TBD	TBD	mA
Active Operating Current (OV_{DD})—133MHz	I_{ODD}		TBD	TBD	mA
Active Operating Current (V_{DD})—200MHz	I_{DD}		400	610	mA
Active Operating Current (OV_{DD})—200MHz	I_{ODD}		35	40	mA
Active Operating Current (V_{DD})—266MHz	I_{DD}		TBD	TBD	mA
Active Operating Current (OV_{DD})—266MHz	I_{ODD}		TBD	TBD	mA
PLL V_{DD} Input current	I_{PLL}		16	23	mA

Note:

1. Maximum power is characterized at V_{DD} = 2.7V, OV_{DD} = 3.6V, T_C = 85°C, across the silicon process (worse case to best case), while running an application designed to maximize power consumption. The specification at 200MHz corresponds to CPU = 200 MHz, PLB = 100MHz, OPB = EBC = 50MHz. The 266MHz maximum power was measured with CPU = 266.6MHz, PLB =133.3MHz, OPB = EBC = 66.6MHz.
2. AV_{DD} should be derived from V_{DD} using the following circuit:



L1 – 2.2µH SMT inductor (equivalent to MuRata LQH3C2R2M34) or SMT chip ferrite bead (equivalent to MuRata BLM31A700S)

C1 – 3.3 µF SMT tantalum

C2 – 0.1µF SMT monolithic ceramic capacitor with X7R dielectric or equivalent

C3 – 0.01µF SMT monolithic ceramic capacitor with X7R dielectric or equivalent

Test Conditions

Clock timing and switching characteristics are specified in accordance with operating conditions shown in the table “Recommended DC Operating Conditions.” AC specifications are characterized at OV_{DD} = 3V and T_J = +85°C with the 50pF test load shown in the figure at right.

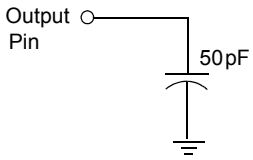
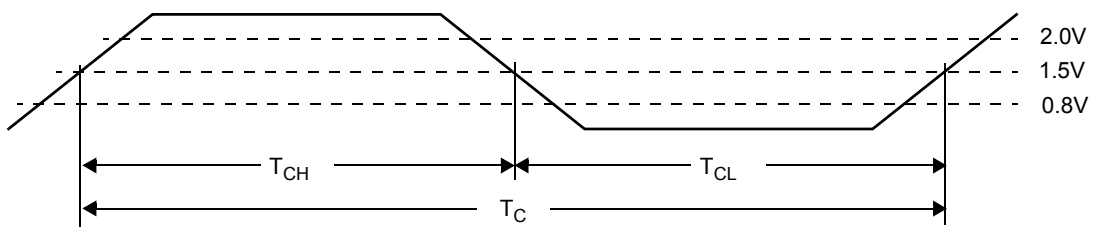


Table 11. Clocking Specifications

Symbol	Parameter	Min	Max	Units
CPU				
PF_C	Processor clock frequency	133.33/200/266.66		MHz
PT_C	Processor clock period	7.5/5/3.75		ns
SysClk Input				
SCF_C	Clock input frequency	25	66.66	MHz
SCT_C	Clock period	15	40	ns
SCT_{CS}	Clock edge stability (phase jitter, cycle to cycle)		± 0.15	ns
SCT_{CH}	Clock input high time	40% of nominal period	60% of nominal period	ns
SCT_{CL}	Clock input low time	40% of nominal period	60% of nominal period	ns
Note: Input slew rate > 2V/ns				
MemClkOut Output				
$MCOF_C$	Clock output frequency @ PF_C = 133MHz		66.66	MHz
$MCOT_C$	Clock period @ PF_C = 133MHz	15		ns
$MCOF_C$	Clock output frequency @ PF_C = 200MHz		100	MHz
$MCOT_C$	Clock period @ PF_C = 200MHz	10		ns
$MCOF_C$	Clock output frequency @ PF_C = 266MHz		133.33	MHz
$MCOT_C$	Clock period @ PF_C = 266MHz	7.5		ns
$MCOT_{CS}$	Clock edge stability (phase jitter, cycle to cycle)		± 0.2	ns
$MCOT_{CH}$	Clock output high time	45% of nominal period	55% of nominal period	ns
$MCOT_{CL}$	Clock output low time	45% of nominal period	55% of nominal period	ns
Other Clocks				
$VCOF_C$	VCO frequency	400	800	MHz
$PLBF_C$	PLB frequency @ PF_C = 133MHz		66.66	MHz
$PLBF_C$	PLB frequency @ PF_C = 200MHz		100	MHz
$PLBF_C$	PLB frequency @ PF_C = 266MHz		133.33	MHz
$OPBF_C$	OPB frequency @ PF_C = 133MHz		33.33	MHz
$OPBF_C$	OPB frequency @ PF_C = 200MHz		50	MHz
$OPBF_C$	OPB frequency @ PF_C = 266MHz		66.66	MHz

Figure 5. Timing Waveform



Spread Spectrum Clocking

Care must be taken when using a spread spectrum clock generator (SSCG) with the PPC405CR. This controller uses a PLL for clock generation inside the chip. The accuracy with which the PLL follows the SSCG is referred to as tracking skew. The PLL bandwidth and phase angle determine how much tracking skew there is between the SSCG and the PLL for a given frequency deviation and modulation frequency. When using an SSCG with the PPC405CR the following conditions must be met:

- The frequency deviation must not violate the minimum clock cycle time. Therefore, when operating the PPC405CR with one or more internal clocks at their maximum supported frequency, the SSCG can only lower the frequency.
- The maximum frequency deviation cannot exceed –3%, and the modulation frequency cannot exceed 40 kHz. In some cases, on-board PPC405CR peripherals impose more stringent requirements (see Note 1).
- Use the peripheral bus clock (PerClk) for logic that is synchronous to the peripheral bus since this clock tracks the modulation.
- Use the SDRAM MemClkOut since it also tracks the modulation.

Notes:

1. The serial port baud rates are synchronous to the modulated clock. The serial port has a tolerance of approximately 1.5% on baud rate before framing errors begin to occur. The 1.5% tolerance assumes that the connected device is running at precise baud rates. If an external serial clock is used the baud rate is unaffected by the modulation.
2. IIC operation is unaffected.

Caution: It is up to the system designer to ensure that any SSCG used with the PPC405CR meets the above requirements and does not adversely affect other aspects of the system.

Table 12. Peripheral Interface Clock Timings

Parameter	Min	Max	Units
PerClk output frequency—133MHz	–	33.33	MHz
PerClk period—133MHz	30	–	ns
PerClk output frequency—200MHz	–	50	MHz
PerClk period—200MHz	20	–	ns
PerClk output frequency—266MHz	–	66.66	MHz
PerClk period—266MHz	15	–	ns
PerClk output high time	45% of nominal period	55% of nominal period	ns
PerClk output low time	45% of nominal period	55% of nominal period	ns
PerClk clock edge stability (phase jitter, cycle to cycle)		± 0.3	ns
UARTSerClk input frequency (Note 1)	–	$1000/(2T_{OPB}+2ns)$	MHz
UARTSerClk period	$2T_{OPB}+2$	–	ns
UARTSerClk input high time	$T_{OPB}+1$	–	ns
UARTSerClk input low time	$T_{OPB}+1$	–	ns
TmrClk input frequency—133MHz	–	33.33	MHz
TmrClk period—133MHz	30	–	ns
TmrClk input frequency—200MHz	–	50	MHz
TmrClk period—200MHz	20	–	ns
TmrClk input frequency—266MHz	–	66.66	MHz
TmrClk period—266MHz	15	–	ns
TmrClk input high time	40% of nominal period	60% of nominal period	ns
TmrClk input low time	40% of nominal period	60% of nominal period	ns

Notes:

1. T_{OPB} is the period in ns of the OPB clock. The internal OPB clock runs at 1/2 the frequency of the PLB clock. The maximum OPB clock frequency is 50MHz for 200MHz parts and 66.66MHz.for 266MHz parts.

Figure 6. Input Setup and Hold Waveform

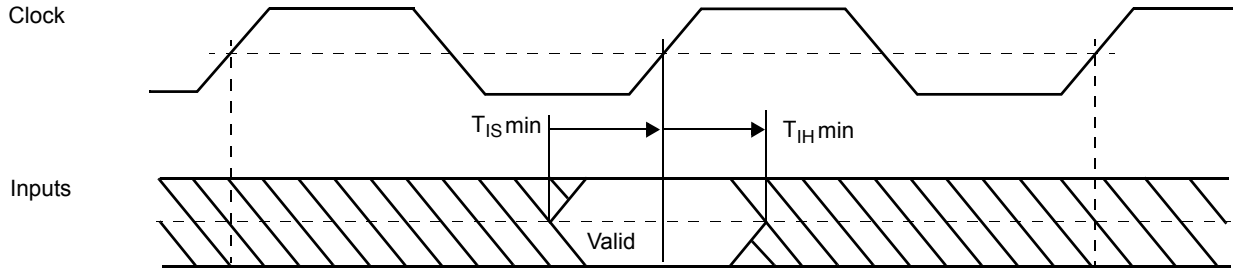
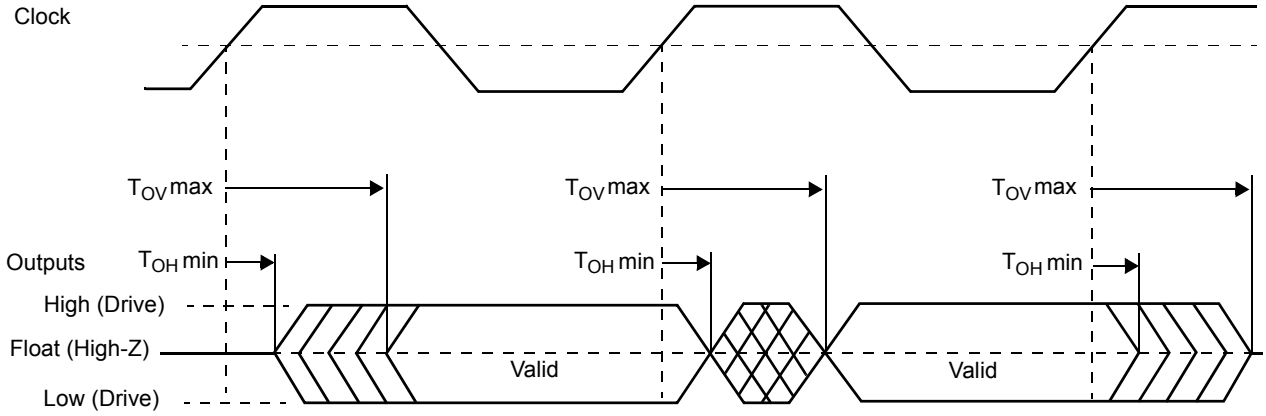


Figure 7. Output Delay and Float Timing Waveform



Notes: 1. In all of the following I/O Specifications tables a timing value of na means “not applicable” and dc means “don’t care.”
2. See “Test Conditions” on page 31 for output capacitive loading.
3. I/O H is specified at 2.4V; I/O L is specified at 0.4V

Table 13. I/O Specifications—All speeds

Signal	Input (ns)		Output (ns)		Output Current (mA)		Clock	Notes
	Setup Time (T_{IS} min)	Hold Time (T_{IH} min)	Valid Delay (T_{OV} max)	Hold Time (T_{OH} min)	I/O H (min)	I/O L (min)		
Internal Peripheral Interface								
IICSCL	n/a	n/a	n/a	n/a	19	12		
IICSDA	n/a	n/a	n/a	n/a	19	12		
UART0_CTS	n/a	n/a			12	8		
UART0_DCD	n/a	n/a			12	8		
UART0_DSR	n/a	n/a			12	8		
UART0_DTR					12	8		
UART0_RI	n/a	n/a			12	8		
UART0_RTS			n/a	n/a	12	8		
UART0_Rx	n/a	n/a			12	8		
UART0_Tx			n/a	n/a	12	8		
UART1_RTS [UART1_DTR]			n/a	n/a	12	8		
UART1_DSR [UART1_CTS]	n/a	n/a			n/a	n/a		
UART1_Rx	n/a	n/a			n/a	n/a		
UART1_Tx			n/a	n/a	12	8		
UARTSerClk	n/a	n/a			n/a	n/a		
Interrupts Interface								
IRQ0:6[GPIO17:23]					12	8		
JTAG Interface								
TCK					n/a	n/a		async
TDI					n/a	n/a		async
TDO					12	8		async
TMS					n/a	n/a		async
TRST					n/a	n/a		async
System Interface								
DrvrInh1:2	dc	dc	n/a	n/a	n/a	n/a		
GPIO1[TS1E] GPIO2[TS2E] GPIO3[TS1O] GPIO4[TS2O] GPIO5[TS3] GPIO6[TS4] GPIO7[TS5] GPIO8[TS6] GPIO9[TrcClk]					12	8		
Halt	dc	dc	n/a	n/a	n/a	n/a		async
RcvrInh	dc	dc	n/a	n/a	n/a	n/a		
SysClk			n/a	n/a	n/a	n/a		
SysErr			n/a	n/a	12	8		async
SysReset			10	1	12	8		async
TestEn	dc	dc	n/a	n/a	n/a	n/a		async
TmrClk	dc	dc	n/a	n/a	n/a	n/a		async

Table 14. I/O Specifications—133 and 200MHz

Notes:
1. The SDRAM command interface is configurable through SDRAM0_TR[LDF] to provide a 2 to 4 cycle delay before the command is used by SDRAM.
2. SDRAM I/O timings are specified relative to a MemClkOut terminated into a lumped 10pF load.
3. SDRAM interface hold times are guaranteed at the PPC405CR package pin. System designers must use the PPC405CR IBIS model (available from **www.amcc.com**) to ensure their clock distribution topology minimizes loading and reflections, and that the relative delays on clock wiring do not exceed the delays on other SDRAM signal wiring.
4. PerClk rising edge at package pin with a 10pF load trails the internal PLB clock by approximately 0.8ns.
5. I/O H is specified at 2.4 V and I/O L is specified at 0.4 V.

Signal	Input (ns)		Output (ns)		Output Current (mA)		Clock	Notes
	Setup Time (T_{IS} min)	Hold Time (T_{IH} min)	Valid Delay (T_{OV} max)	Hold Time (T_{OH} min)	I/O H (min)	I/O L (min)		
SDRAM Interface								
BA1:0	n/a	n/a	7.3	1	19	12	MemClkOut	1, 2
BankSel0:3	n/a	n/a	5.8	1	19	12	MemClkOut	2
CAS	n/a	n/a	7.3	1	19	12	MemClkOut	1, 2
ClkEn0:1	n/a	n/a	4.7	1	40	25	MemClkOut	2
DQM0:3	n/a	n/a	6.2	1	19	12	MemClkOut	2
DQMCB	n/a	n/a	6	1	19	12	MemClkOut	2
ECC0:7	2	1	6	1	19	12	MemClkOut	2
MemAddr12:0	n/a	n/a	7.8	1	19	12	MemClkOut	1, 2
MemData0:31	2	1	6.2	1	19	12	MemClkOut	2
RAS	n/a	n/a	7.4	1	19	12	MemClkOut	1, 2
WE	n/a	n/a	7.4	1	19	12	MemClkOut	1, 2
External Slave Peripheral Interface								
DMAAck0:3	n/a	n/a	8	0	12	8	PerClk	
DMAReq0:3	dc	dc	n/a	n/a	n/a	n/a	PerClk	
EOT0:3/TC0:3	dc	dc	9	0	12	8	PerClk	
PerAddr0:31	4	1	10	0	19	12	PerClk	
PerBLast	4	1	8	0	12	8	PerClk	
PerCS0 PerCS1:7[GPIO10:16]	n/a	n/a	9	0	12	8	PerClk	
PerData0:31	6	1	10	0	19	12	PerClk	
PerOE	n/a	n/a	8	0	12	8	PerClk	
PerPar0:3	4	1	10.5	0	19	12	PerClk	
PerR/W	5	1	8	0	12	8	PerClk	
PerReady	9	1	n/a	n/a	n/a	n/a	PerClk	
PerWBE0:3	4	1	8	0	12	8	PerClk	
External Master Peripheral Interface								
BusReq	n/a	n/a	8	0	12	8	PerClk	
ExtAck	n/a	n/a	8	0	12	8	PerClk	
ExtReq	6	1	n/a	n/a	n/a	n/a	PerClk	
ExtReset	n/a	n/a	8	0	19	12	PerClk	
HoldAck	n/a	n/a	8	0	12	8	PerClk	
HoldPri	4	1	n/a	n/a	n/a	n/a	PerClk	
HoldReq	6	1	n/a	n/a	n/a	n/a	PerClk	
PerClk	n/a	n/a	0.9	0.9	19	12	PLB Clk	4
PerErr	4	1	n/a	n/a	n/a	n/a	PerClk	

Table 15. I/O Specifications—266MHz

Notes:
1. The SDRAM command interface is configurable through SDRAM0_TR[LDF] to provide a 2 to 4 cycle delay before the command is used by SDRAM.
2. SDRAM I/O timings are specified relative to a MemClkOut terminated into a lumped 10pF load.
3. SDRAM interface hold times are guaranteed at the PPC405CR package pin. System designers must use the PPC405CR IBIS model (available from **www.amcc.com**) to ensure their clock distribution topology minimizes loading and reflections, and that the relative delays on clock wiring do not exceed the delays on other SDRAM signal wiring.
4. PerClk rising edge at package pin with a 10pF load trails the internal PLB clock by approximately 0.8ns.
5. I/O H is specified at 2.4 V and I/O L is specified at 0.4 V.

Signal	Input (ns)		Output (ns)		Output Current (mA)		Clock	Notes
	Setup Time (T_{IS} min)	Hold Time (T_{IH} min)	Valid Delay (T_{OV} max)	Hold Time (T_{OH} min)	I/O H (min)	I/O L (min)		
SDRAM Interface								
BA1:0	n/a	n/a	5.5	1	19	12	MemClkOut	1, 2
BankSel0:3	n/a	n/a	4.5	1	19	12	MemClkOut	2
CAS	n/a	n/a	5.5	1	19	12	MemClkOut	1, 2
ClkEn0:1	n/a	n/a	3.9	1	40	25	MemClkOut	2
DQM0:3	n/a	n/a	4.9	1	19	12	MemClkOut	2
DQMCB	n/a	n/a	4.7	1	19	12	MemClkOut	2
ECC0:7	1.5	1	4.7	1	19	12	MemClkOut	2
MemAddr12:0	n/a	n/a	5.9	1	19	12	MemClkOut	1, 2
MemData0:31	1.5	1	4.8	1	19	12	MemClkOut	2
RAS	n/a	n/a	5.6	1	19	12	MemClkOut	1, 2
WE	n/a	n/a	5.6	1	19	12	MemClkOut	1, 2
External Slave Peripheral Interface								
DMAAck0:3	n/a	n/a	6	0	12	8	PerClk	
DMAReq0:3	dc	dc	n/a	n/a	n/a	n/a	PerClk	
EOT0:3/TC0:3	dc	dc	8	0	12	8	PerClk	
PerAddr0:31	3	1	8	0	19	12	PerClk	
PerBLast	3.5	1	6	0	12	8	PerClk	
PerCS0 PerCS1:7[GPIO10:16]	n/a	n/a	6	0	12	8	PerClk	
PerData0:31	5	1	8	0	19	12	PerClk	
PerOE	n/a	n/a	6	0	12	8	PerClk	
PerPar0:3	3.5	1	8	0	19	12	PerClk	
PerR/W	4	1	6	0	12	8	PerClk	
PerReady	6.5	1	n/a	n/a	n/a	n/a	PerClk	
PerWBE0:3	3	1	6	0	12	8	PerClk	
External Master Peripheral Interface								
BusReq	n/a	n/a	6	0	12	8	PerClk	
ExtAck	n/a	n/a	6	0	12	8	PerClk	
ExtReq	5	1	n/a	n/a	n/a	n/a	PerClk	
ExtReset	n/a	n/a	6	0	19	12	PerClk	
HoldAck	n/a	n/a	6	0	12	8	PerClk	
HoldPri	3	1	n/a	n/a	n/a	n/a	PerClk	
HoldReq	5	1	n/a	n/a	n/a	n/a	PerClk	
PerClk	n/a	n/a	0.9	0.9	19	12	PLB Clk	4
PerErr	3	1	n/a	n/a	n/a	n/a	PerClk	

Strapping

When the SysReset input is driven low by an external device (system reset), the state of certain I/O pins is read to enable default initial conditions prior to PPC405CR start-up. The actual capture instant is the nearest SysClk edge before the deassertion of reset. These pins must be strapped using external pull-up (logical 1) or pull-down (logical 0) resistors to select the desired default conditions. The recommended pull-up is 3kΩ to +3.3V or 10kΩ to +5V. The recommended pull-down is 1KΩ to GND. These pins are use for strap functions only during reset. They are used for other signals during normal operation. The following table lists the strapping pins along with their functions and strapping options. The signal names assigned to the pins for normal operation follow the pin number.

Table 16. Strapping Pin Assignments (Sheet 1 of 2)

Function	Option	Ball Strapping		
PLL Tuning[1] for $6 \leq M \leq 7$ use choice 3 for $7 < M \leq 12$ use choice 5 for $12 < M \leq 32$ use choice 6 See Note.		**W15** UART0_Tx	**U13** UART0_DTR	**V20** UART0_RTS
	Choice 1; TUNE[5:0] = 010001	0	0	0
	Choice 2; TUNE[5:0] = 010010	0	0	1
	Choice 3; TUNE[5:0] = 010011	0	1	0
	Choice 4; TUNE[5:0] = 010100	0	1	1
	Choice 5; TUNE[5:0] = 010101	1	0	0
	Choice 6; TUNE[5:0] = 010110	1	0	1
	Choice 7; TUNE[5:0] = 010111	1	1	0
	Choice 8; TUNE[5:0] = 100100	1	1	1
PLL Forward Divider[2]		**C16** DMAAck0	**B17** DMAAck1	
	Bypass mode	0	0	
	Divide by 3	0	1	
	Divide by 4	1	0	
	Divide by 6	1	1	
PLL Feedback Divider[2]		**B16** DMAAck2	**A14** DMAAck3	
	Divide by 1	0	0	
	Divide by 2	0	1	
	Divide by 3	1	0	
	Divide by 4	1	1	
PLB Divider from CPU[2, 3]		**B18** GPIO1[TS1E]	**D16** GPIO2[TS2E]	
	Divide by 1	0	0	
	Divide by 2	0	1	
	Divide by 3	1	0	
	Divide by 4	1	1	
OPB Divider from PLB[2]		**T4** HoldAck	**U5** ExtAck	
	Divide by 1	0	0	
	Divide by 2	0	1	
	Divide by 3	1	0	
	Divide by 4	1	1	

Table 16. Strapping Pin Assignments (Sheet 2 of 2)

Function	Option	Ball Strapping		
External Bus Divider from PLB[2, 3]		**C17** GPIO3[TS1O]	**P18** GPIO4[TS2O]	
	Divide by 2	0	0	
	Divide by 3	0	1	
	Divide by 4	1	0	
	Divide by 5	1	1	
ROM Width		**Y5** UART1_Tx	**W6** $\overline{\text{UART1_RTS}}$/$\overline{\text{UART1_DTR}}$	
	8-bit ROM	0	0	
	16-bit ROM	0	1	
	32-bit ROM	1	0	
	Reserved	1	1	

Note:

1. The tune bits adjust parameters that control PLL jitter. The recommended values minimize jitter for the PLL implemented in the PPC405CR. These bits are shown for information only; and do not require modification except in special clocking circumstances such as spread spectrum clocking. For details on the use of Spread Spectrum Clock Generators (SSCGs) with the PPC405CR, visit the technical documents area of the AMCC PowerPC web site.
2. Not all combinations of dividers produce valid operating configurations. Frequencies must be within the limits specified in “Clocking Specifications” on page 32. Further requirements are detailed in the Clocking chapter of the *PowerPC 405CR Embedded Processor User’s Manual*.
3. Additional consideration must be given to pins that normally function as Trace signals. Improved design margin can be gained by using three-state buffers instead of strapping resistors, and minimizing trace lengths and stubs.

Document Revision History

Revision	Date	Description
1.01	08/05/04	Initial release
1.02	01/11/05	Add lead-free part numbers.

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